har-flex straight male connected that INFORMATIONS  The straight male connected that INFORMATIONS  Intact spacing to Voltage that the straight male connected that th	Stacking height 1,75mm, 3,25mm from 6 to 100poles, all even numbers stacking height 4,85mm from 6 to 80poles, all even numbers 1,27mm x 1,27mm [0,050"x0,050"]  500V  <25 mOhm ≥ 10x10^9Ω  see derating diagram  -55°C +125°C  SMT  min. 150s > 217°C  min. 30s > 240°C	PCB pad plating The har-flex connectors ar  Stencil recommendation The solder deposition had lideally, the solder deposition The size of the solder stelling general, the thinner stelling the size of the solder stelling the size of the solder stelling general, the thinner stelling the size of the solder stelling the size of t	e solderable with est e solderable on lead s to be placed on the tion has the same lei ncil apertures is dep encils will need large	ablished lead-free SAC / SnNi solution-free pad surfaces like HAL, NiAu, appad area of the contact solder tinength-to-width ratio and center point ending on the thickness of the stern apertures to result in the required or the signal pins is 0,094mm³, for	nes. nt like the PCB pads. encil. d volume of solder paste.
ERAL INFORMATIONS  of contacts  tract spacing t Voltage  tract resistance  rightion resistance  righting current acc. to IEC 60512, at 70°C, 80% derating  righting temperature range  mination technology  low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	stacking height 1,75mm, 3,25mm from 6 to 100poles, all even numbers stacking height 4,85mm from 6 to 80poles, all even numbers 1,27mm x 1,27mm [0,050"x0,050"] 500V <25 mOhm ≥ 10x10^9Ω see derating diagram -55°C +125°C SMT min. 150s > 217°C	Solder paste recommenda The har-flex connectors ar  PCB pad plating The har-flex connectors ar  Stencil recommendation The solder deposition has Ideally, the solder deposition has Ideally, the solder deposition has Ideally, the solder deposition has In general, the thinner stends are the minimum required so For example, this can be	e solderable with est e solderable on lead s to be placed on the tion has the same let ncil apertures is dep encils will need large	ablished lead-free SAC / SnNi solution-free pad surfaces like HAL, NiAu, appad area of the contact solder tinength-to-width ratio and center point ending on the thickness of the stern apertures to result in the required or the signal pins is 0,094mm³, for	nes. It like the PCB pads. encil. d volume of solder paste.
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tact resistance  Ilation resistance  Iking current acc. to IEC 60512, at 70°C, 80% derating  Iking temperature range  Imination technology  It is is in the processing temperature  It is in the pro	<25 mOhm ≥ 10x10^9Ω see derating diagram -55°C +125°C SMT min. 150s > 217°C	The size of the solder ste In general, the thinner ste The minimum required so For example, this can be	ncil apertures is dep encils will need large older paste volume fo	ending on the thickness of the ste r apertures to result in the required or the signal pins is 0,094mm <sup>3</sup> , for	encil. d volume of solder paste.
Ilation resistance rking current acc. to IEC 60512, at 70°C, 80% derating rking temperature range mination technology low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	≥ 10x10^9Ω see derating diagram -55°C +125°C SMT min. 150s > 217°C	In general, the thinner ste The minimum required so For example, this can be	encils will need large older paste volume fo	r apertures to result in the required or the signal pins is 0,094mm³, for	d volume of solder paste.
rking current acc. to IEC 60512, at 70°C, 80% derating rking temperature range mination technology low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	see derating diagram -55°C +125°C  SMT min. 150s > 217°C	The minimum required so For example, this can be	lder paste volume fo	or the signal pins is 0,094mm <sup>3</sup> , for	
rking temperature range mination technology low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	-55°C +125°C SMT min. 150s > 217°C	$\dashv$	achieved with the fol	llowing stencil data :	
mination technology low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	SMT min. 150s > 217°C	Stancil thickness			
low processing temperature c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 150s > 217°C	Stancil thickness		Signal pins	
c. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)		1 101011011 11110N11033	PCB pad size	proposal stencil aperture size	calculated solder paste volume
,		120 µm	1,1 x 0,8 mm	1.05 x 0.75 mm	0,095 mm <sup>3</sup>
arance & creepage distance	0,4mm min.	150 µm	1,1 x 0,8 mm	0,99 x 0,72 mm	0,107 mm³
ertion force (depending on mating connector)	approximately 0,5N/contact		1,1,0,0,0,0,0,0,0,0,0,0,0,0,0,0,0,0,0,0	Hold-downs	
ndrawal force (depending on mating connector)	approximately 0,5N/contact	0. 2011	DOD - 1 1		and and a second
, ,	PL1 : 500 mating cycles	Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume
ing cycles	PL2 : 250 mating cycles	120 µm	2,5 x 1,2 mm	2,45 x 1,15 mm	0,338 mm³
IS - compliant	Yes	150 µm	2,5 x 1,2 mm	2,25 x 1,08 mm	0,365 mm³
dfree	Yes				d solder paste volume by enlarging th
king voltage acc. to to IEC 60664-1	100V / 150V (depending on installation category)	stencil aperture. Depending on the PCB design, the solder depostion may protrude the PCB pads. But to achieve a good sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller			
file acc. UL 1977	ECBT2.E102079	than the PCB pad about 10			cii, the aperture should be smaller
file acc. CSA-C22.2 (for Canada)	ECBT8.E102079	Coplanarity of contacts			
level acc. ECA/IPC/JEDEC J-STD-075	PSL R0	All connectors are tested for coplanarity of contacts and are in the range of 6 pin to 80 pin: ≤ 0,1mm			
level acc. ECA/IPC/JEDEC J-STD-020D	All connectors are tested for copianantly of contacts and are in the range of 6 pin to 60 pin. ≤ 0, min.  82 pin to 100 pin: ≤ 0,15mm				
LATOR MATERIAL		$\exists \overline{}$		62 μι	11 to 100 pin. ≤ 0,15min
		Performance level	1.16		
erial	LCP (liquid crystalline polymer)	Performance level 1 (recommended for majority of applications) Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance and visual inspection.			
or	Black				
classification	UL94-V0				
erial group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)	Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment.  Part number definition: 15 2			
TACT MATERIAL	* * * * *	ran number definition : 15	4		
tact material	Copper alloy	Performance level 2			
ing termination zone	Sn Sn	Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb.  Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance and visual inspection.			
ing cermination zone ing contact sliding side	Au over PdNi (acc. to Performance level)				
		Visual inspection. No abras		ish through to the base material. N	√o functional impairment.
ATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity	y)	Part number definition: 15			
The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.  The current capacity curve is valid for continuous, non	A Heritac Equil - SEEgool.  4	Performance level S4 Defined contact surface of Part number definition: 15	5		
interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.  Control and test procedures according to DIN IEC 60512-5	Electrical load [A]	All Dimensions in Original Size DIN  All rights reserve Department EL PD	A3 1:1	Inspected by Standardisation HOFFMANN	Ref. Sub.  Date 2019-07-10  State Final Release
derating curve at Imax*0,8 (IEC 60512-5-2)	Temperature [°C]	HARTING Electronics GmbH D-32339 Espelkamp	<u> </u>	nale stacking height1.75 , 3.25 a	and 4.85    Doc-Key / EC   100577896/UGD   500000153899   Rev.   D
1 2	3 4	5	6	7	8

